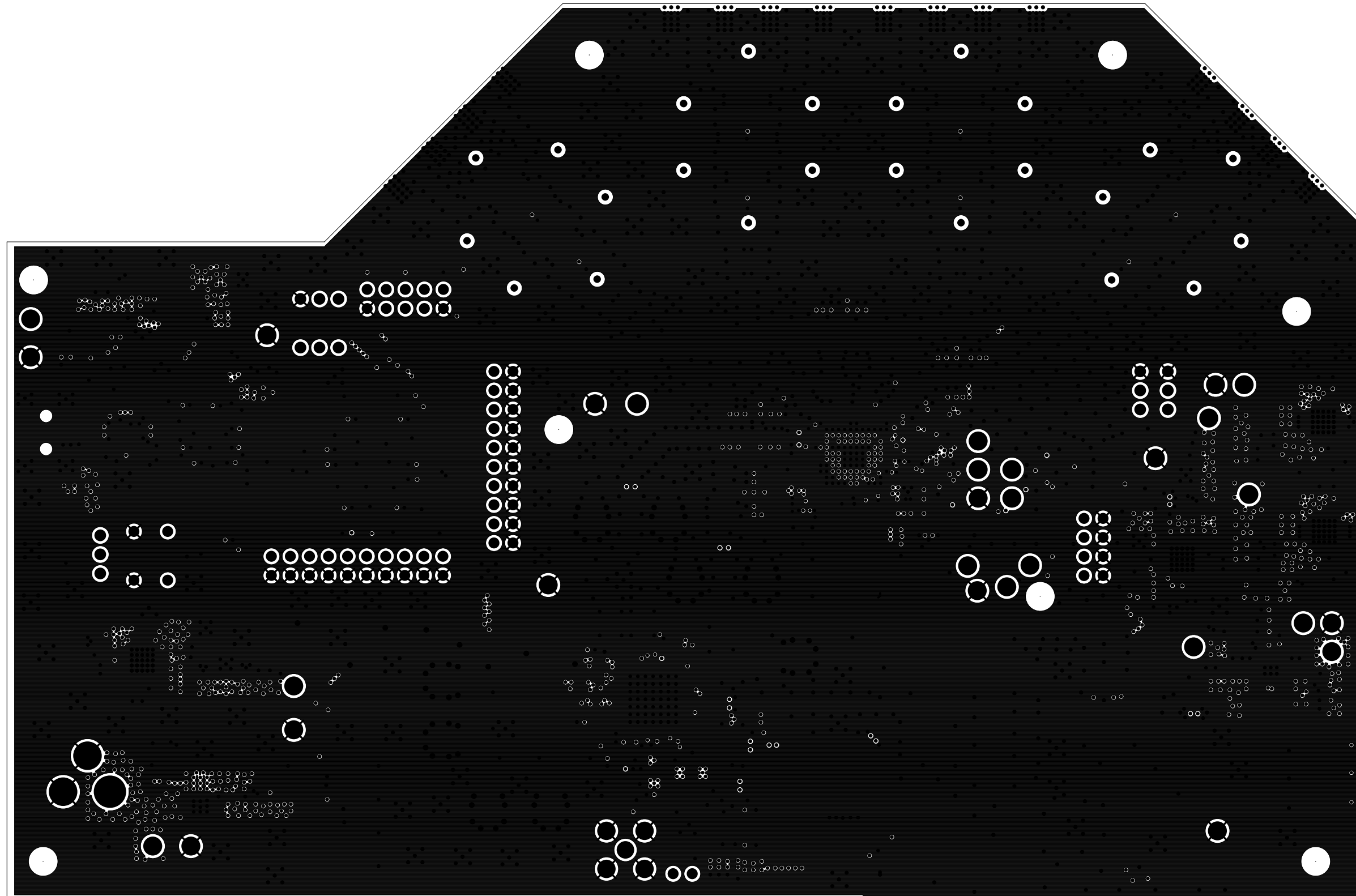
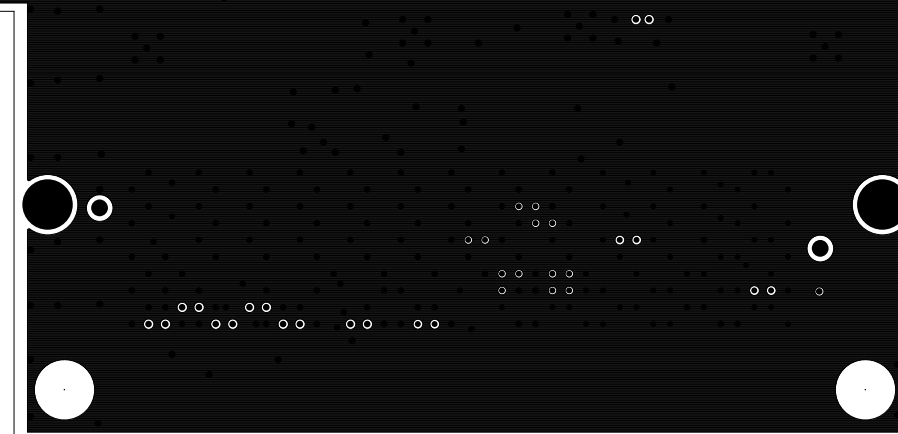
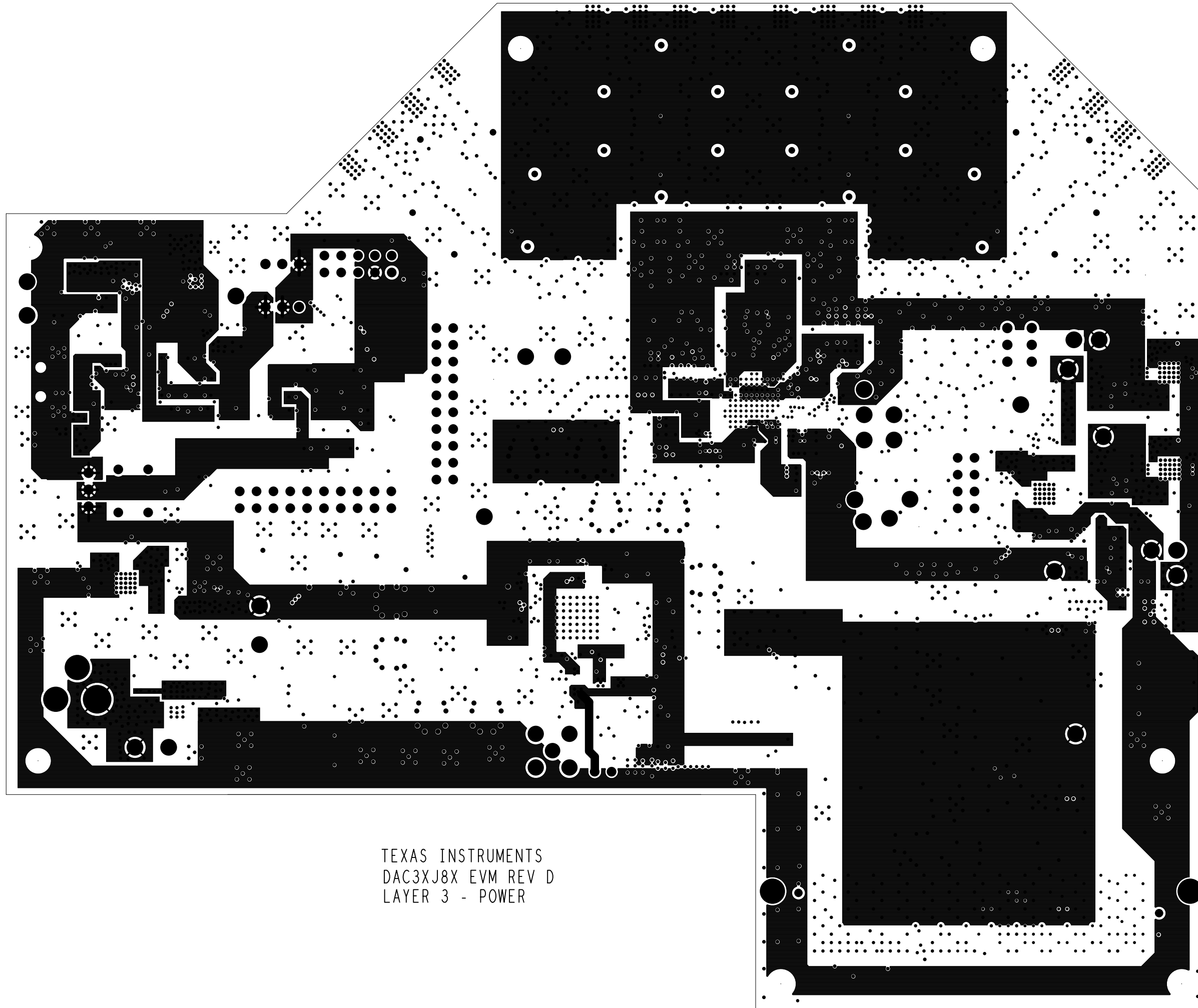


TEXAS INSTRUMENTS
DAC3XJ8X EVM REV D
LAYER 1 (TOP SIDE)

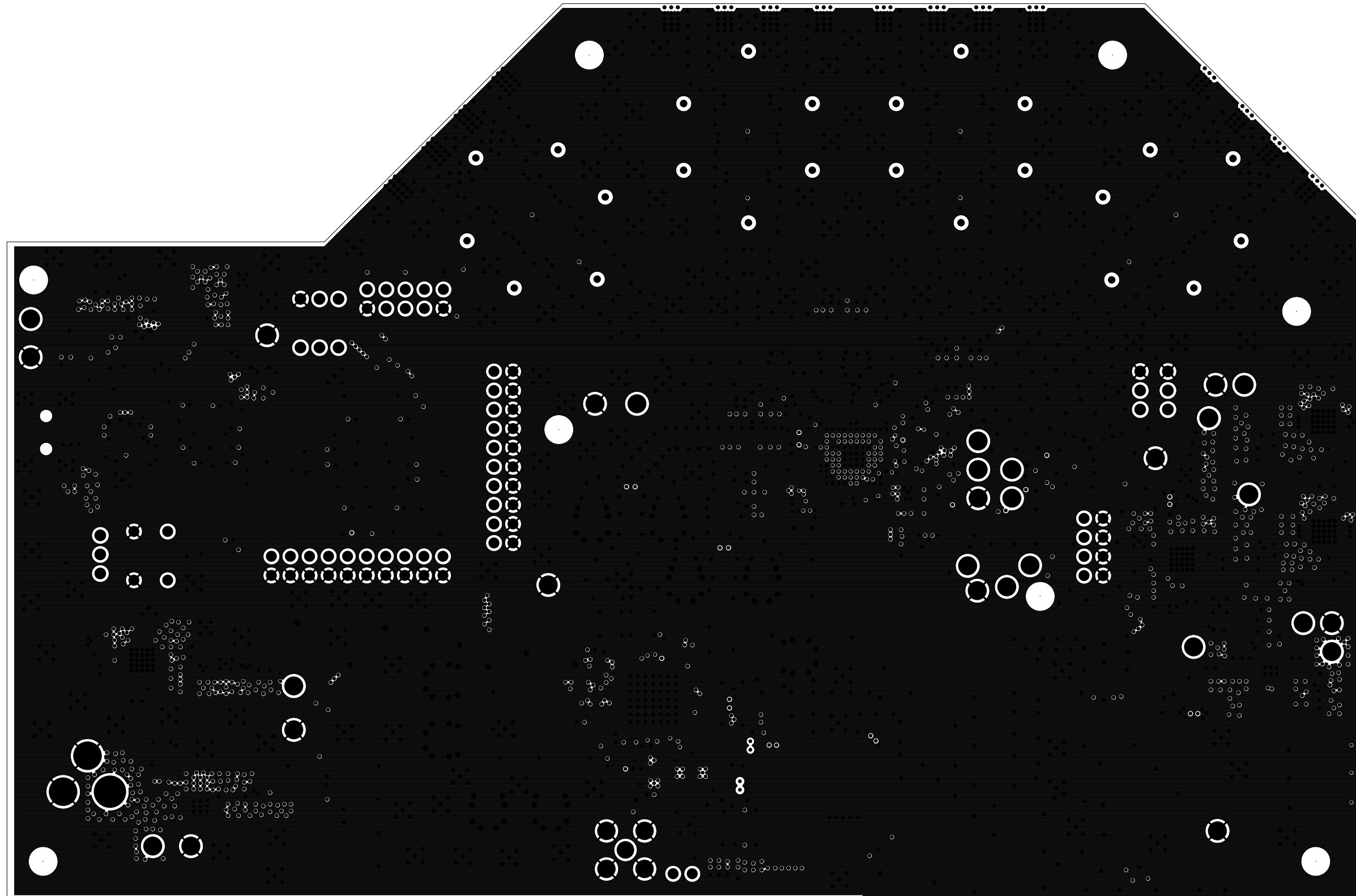


TEXAS INSTRUMENTS
DAC3XJ8X EVM REV D
LAYER 2 - GND

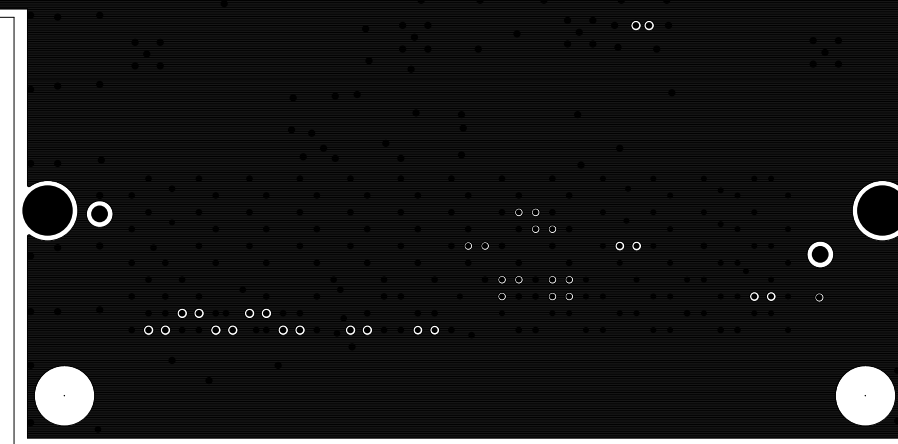


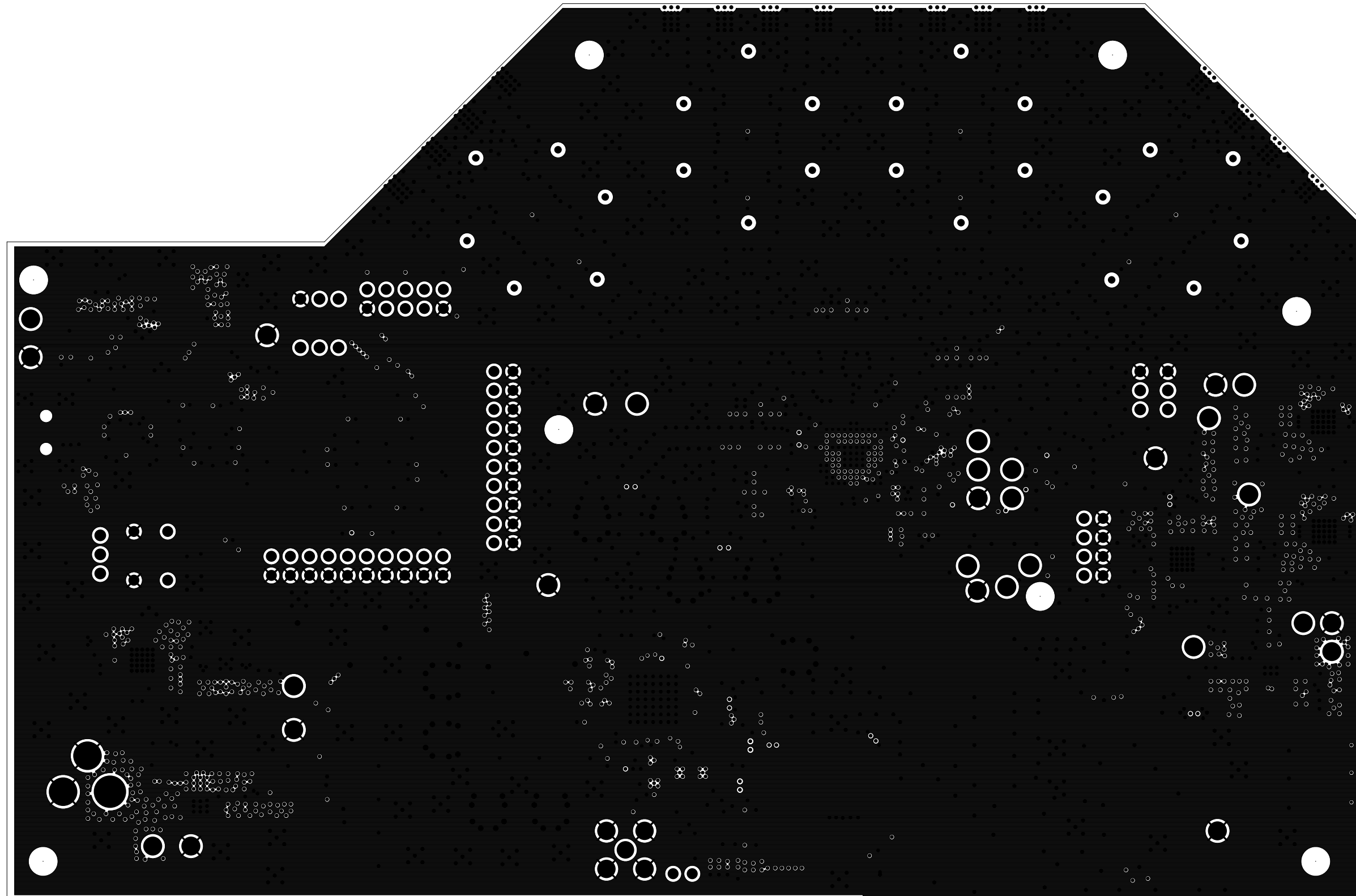


TEXAS INSTRUMENTS
DAC3XJ8X EVM REV D
LAYER 3 - POWER

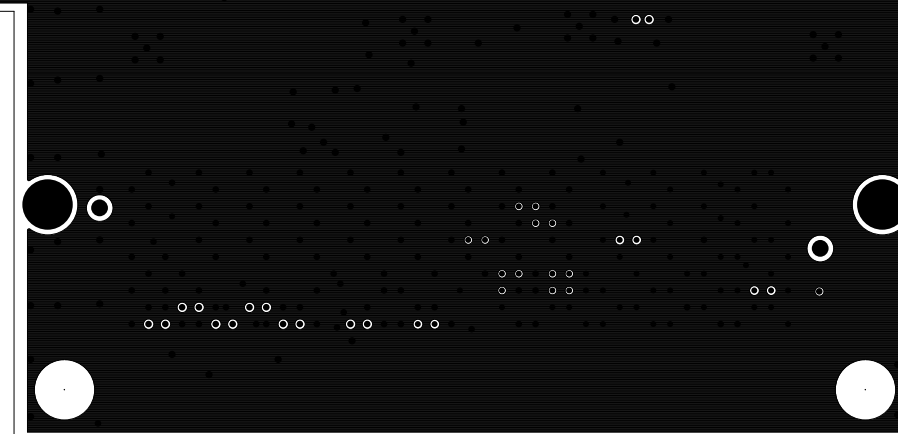


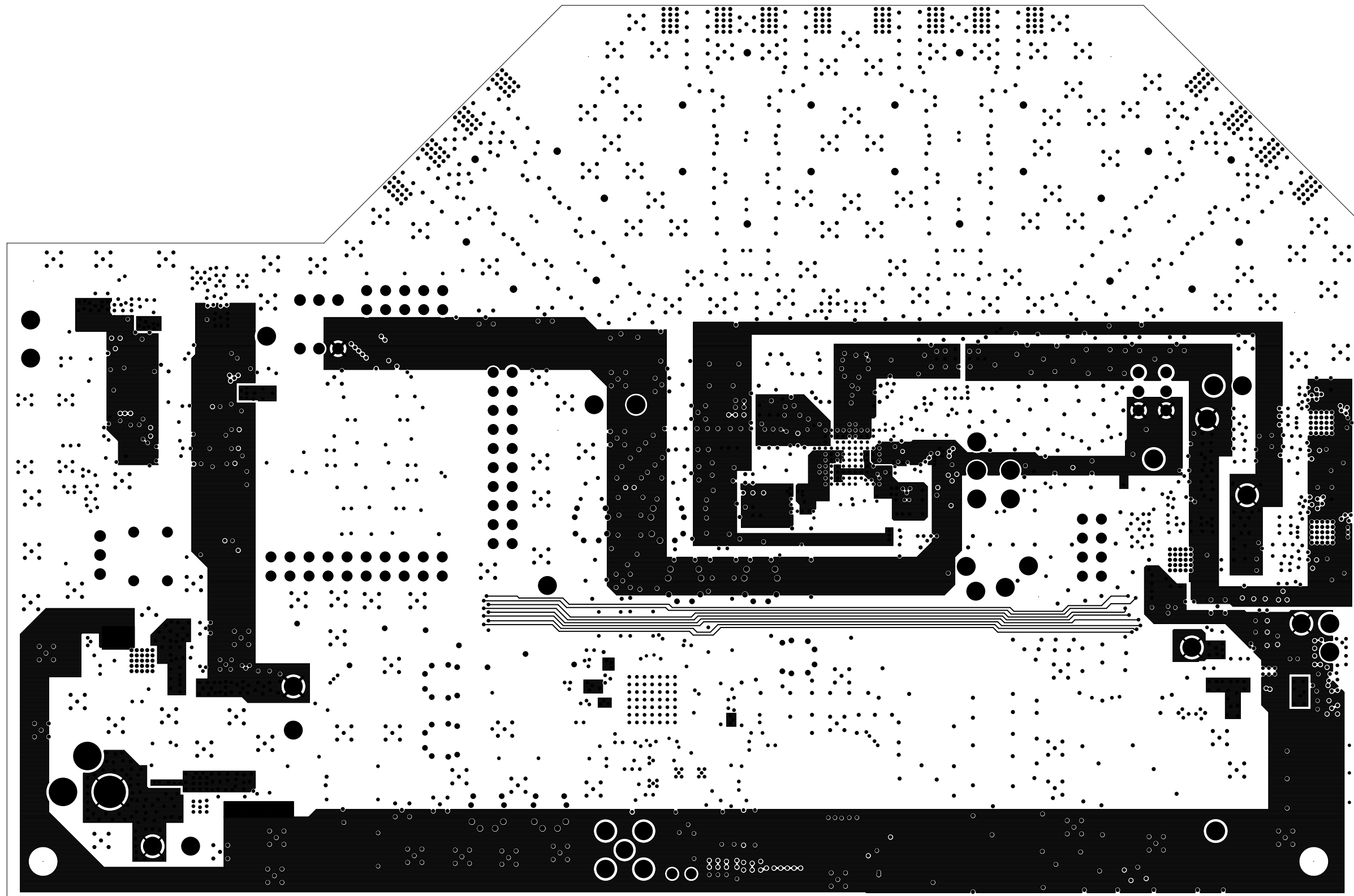
TEXAS INSTRUMENTS
DAC3XJ8X EVM REV D
LAYER 4 - GND



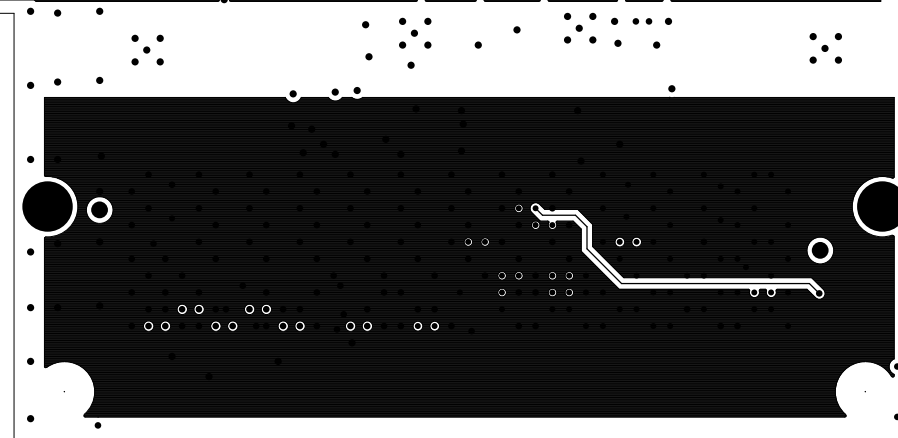


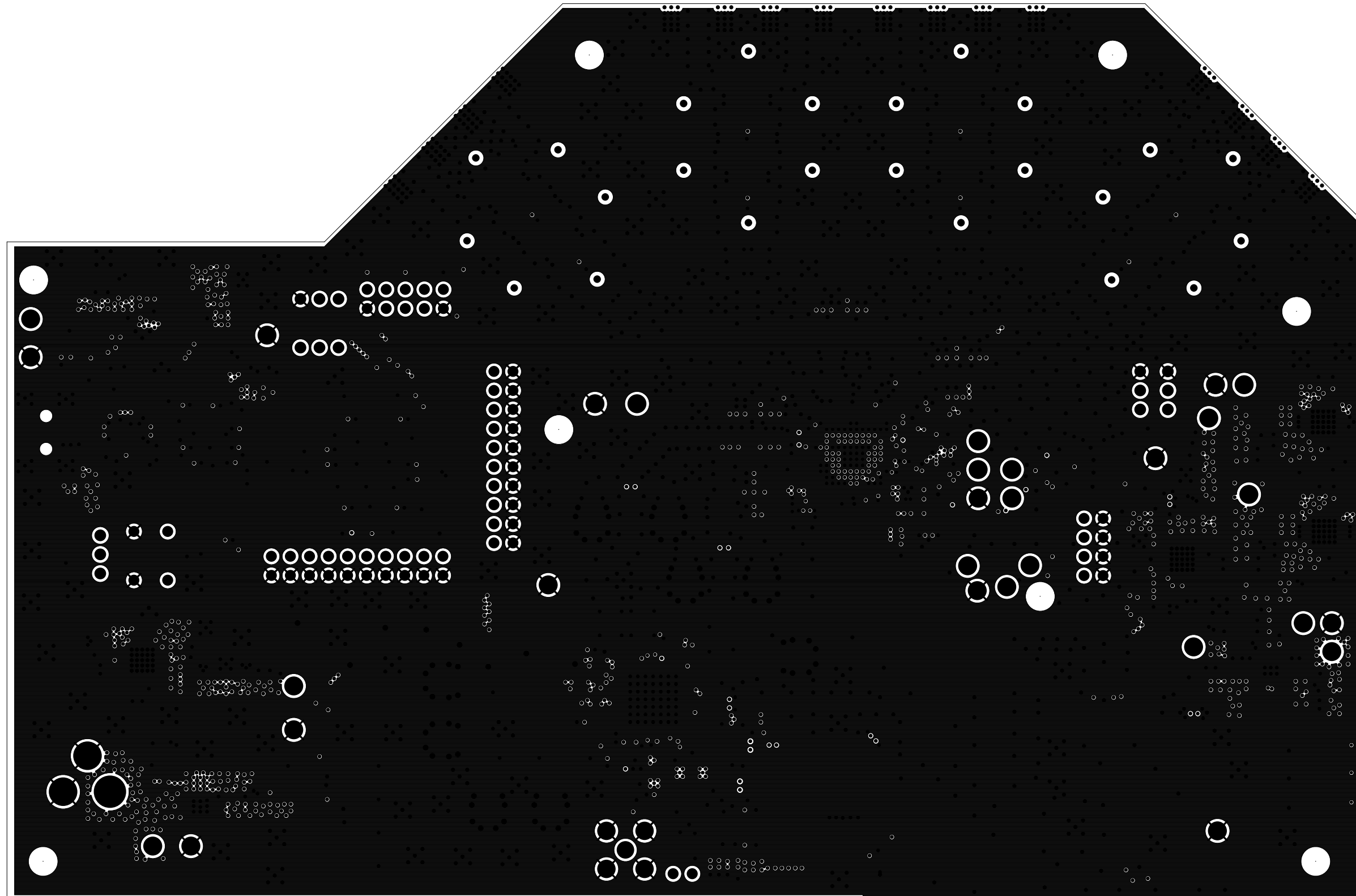
TEXAS INSTRUMENTS
DAC3XJ8X EVM REV D
LAYER 5 - GND



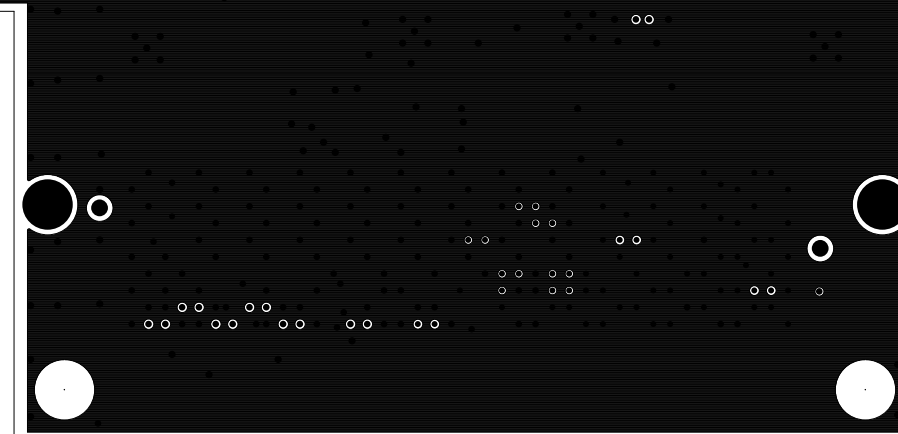


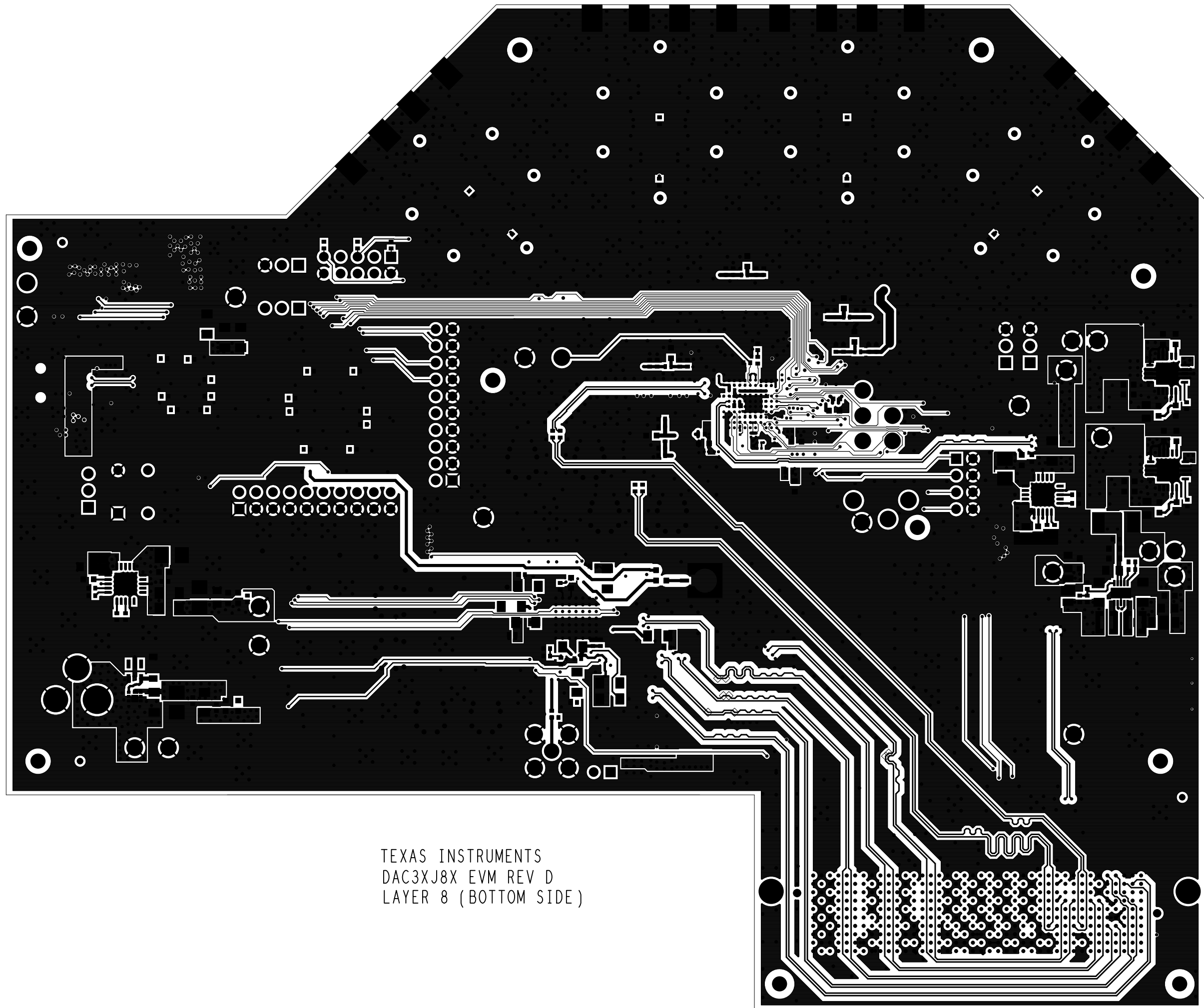
TEXAS INSTRUMENTS
DAC3XJ8X EVM REV D
LAYER 6 - POWER



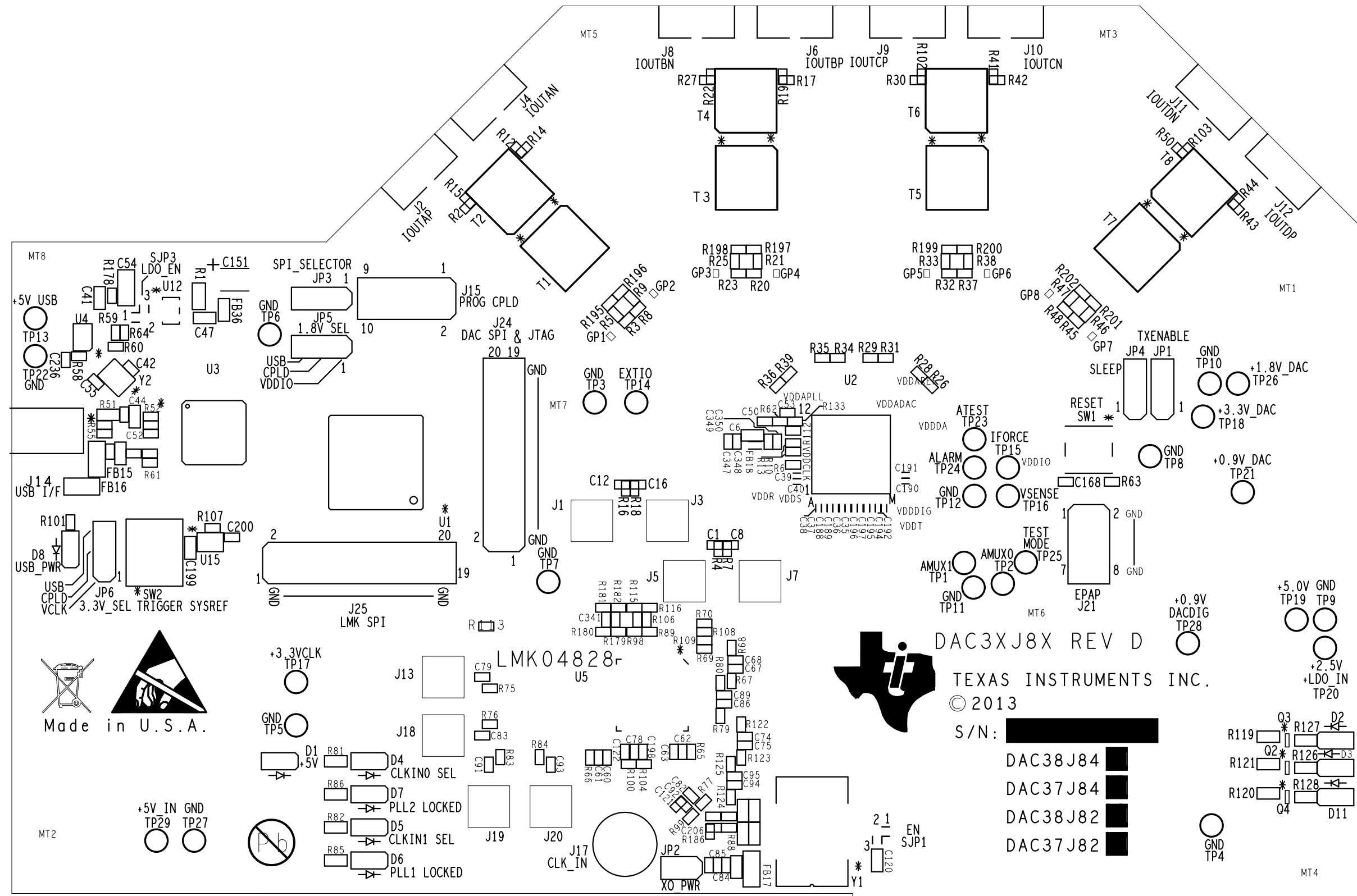


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DAC3XJ8X EVM REV D
LAYER 7 - GND





TEXAS INSTRUMENTS
DAC3XJ8X EVM REV D
LAYER 8 (BOTTOM SIDE)






 Made in U.S.A.



DAC3XJ8X REV D
 TEXAS INSTRUMENTS INC.
 © 2013

S/N: [REDACTED]

- DAC38J84 [REDACTED]
- DAC37J84 [REDACTED]
- DAC38J82 [REDACTED]
- DAC37J82 [REDACTED]

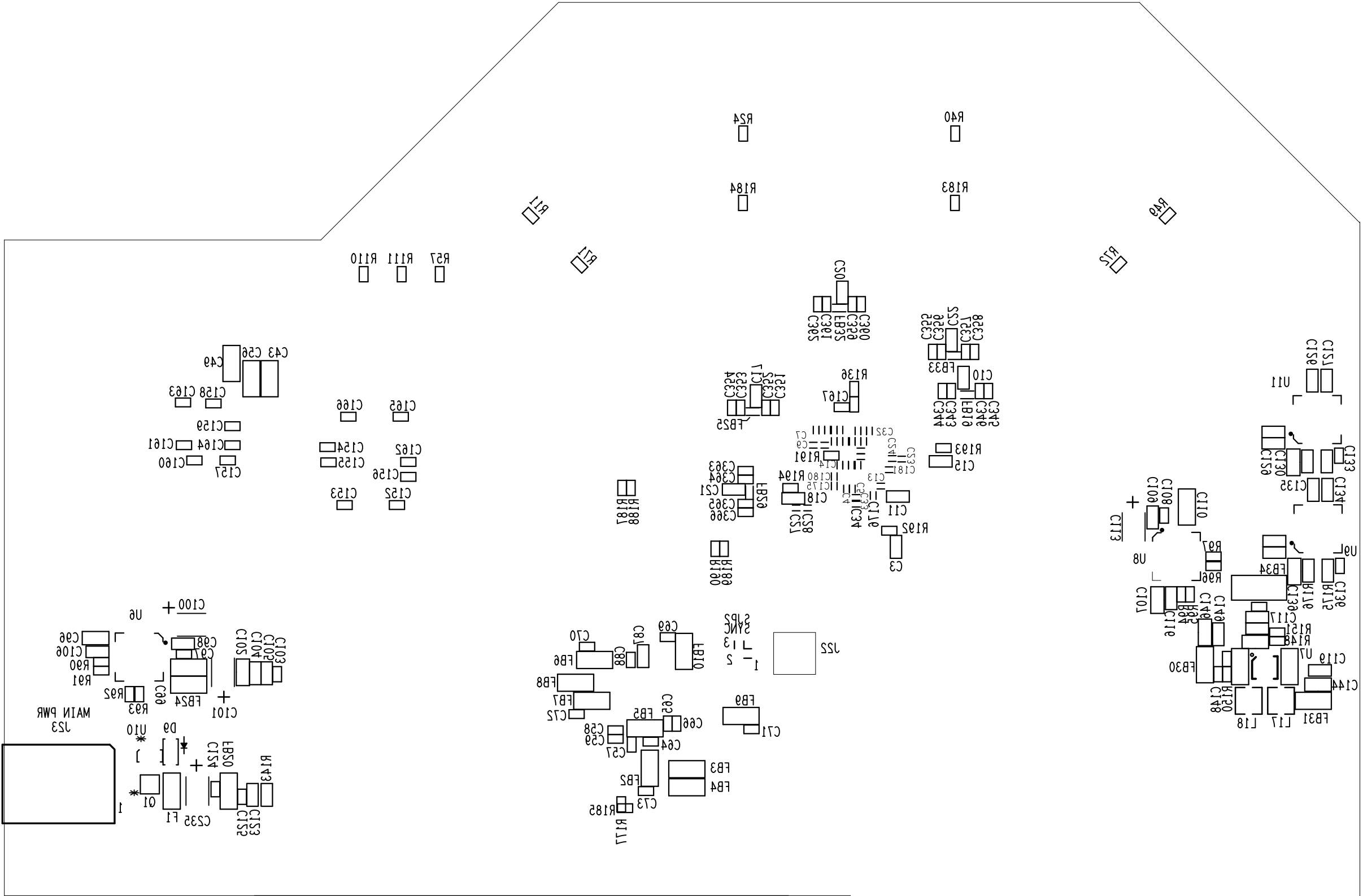
TEXAS INSTRUMENTS
 DAC3XJ8X EVB REV D
 SILKSCREEN TOP

K40

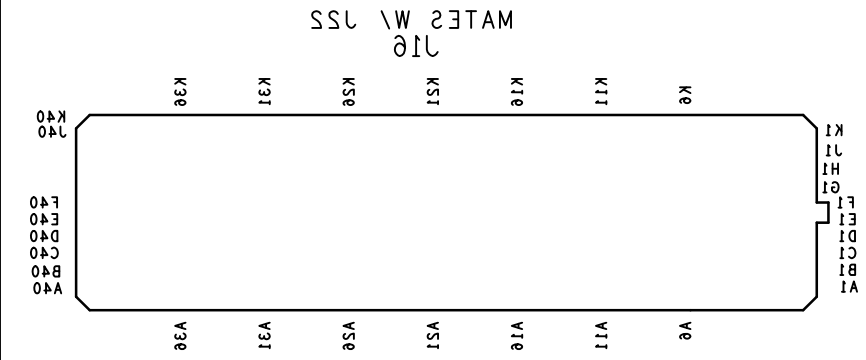
K1

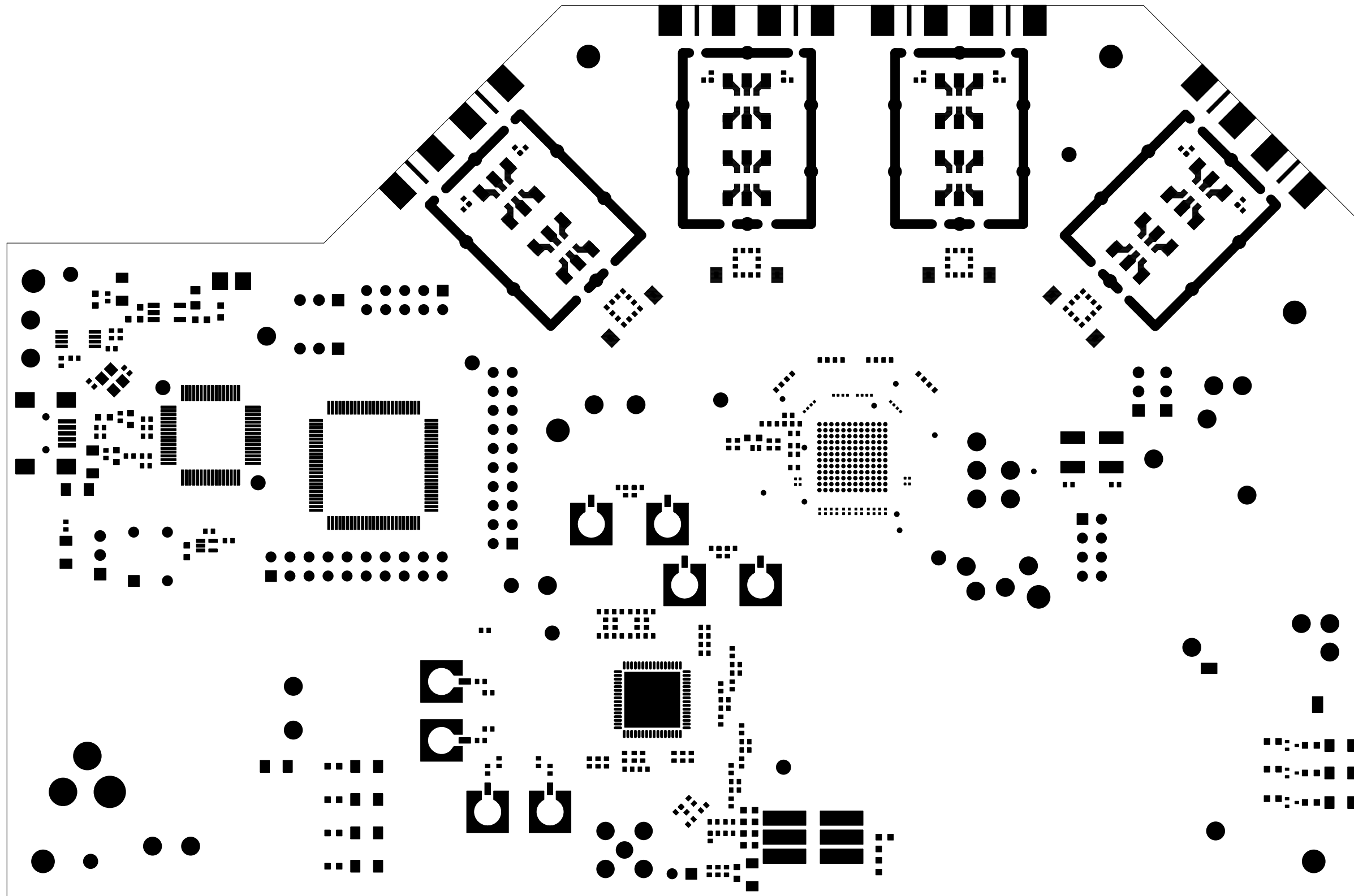
A40

A1



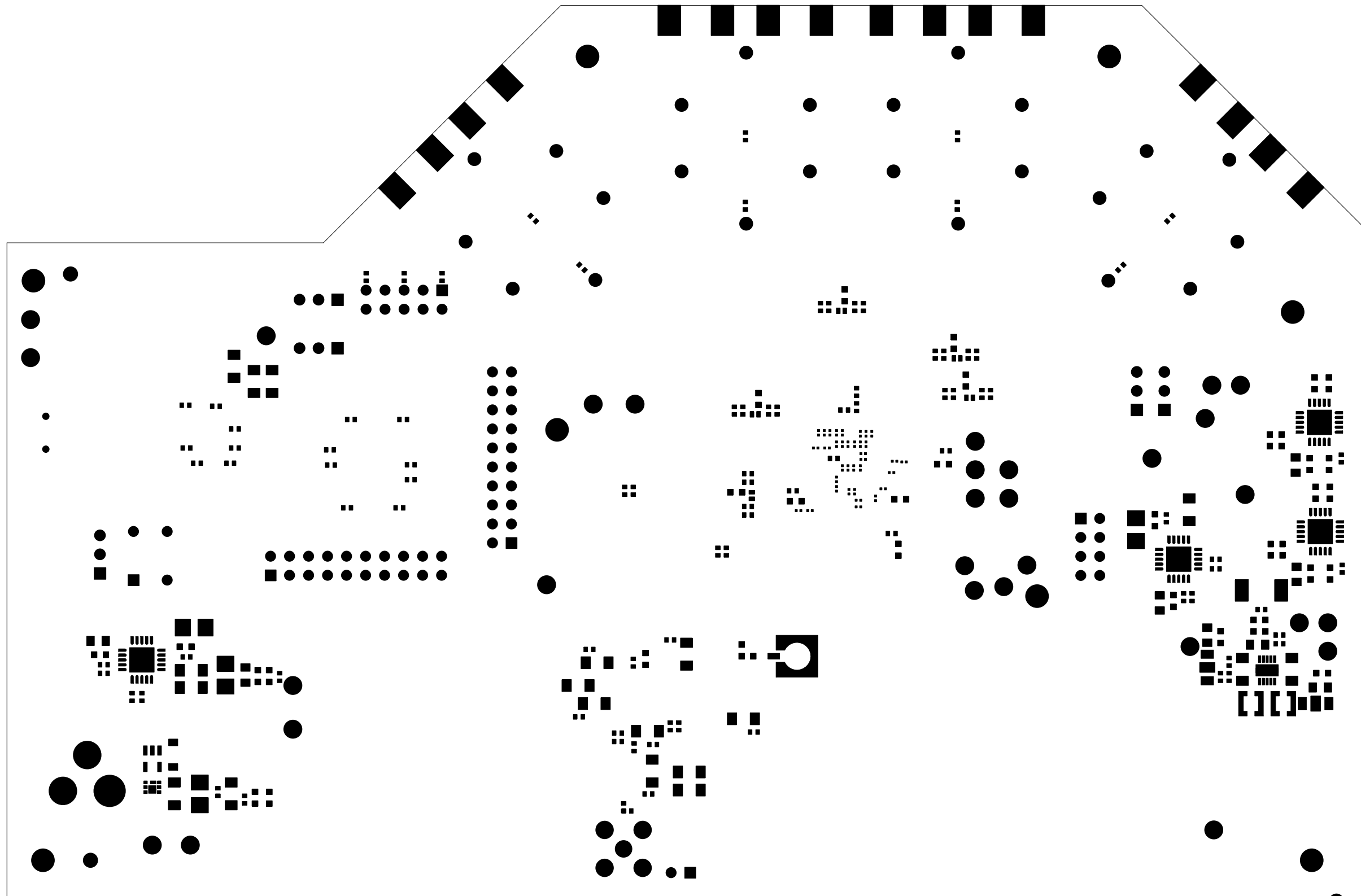
TEXAS INSTRUMENTS
 DAC3XJ8X EVM REV D
 SILKSCREEN BOTTOM





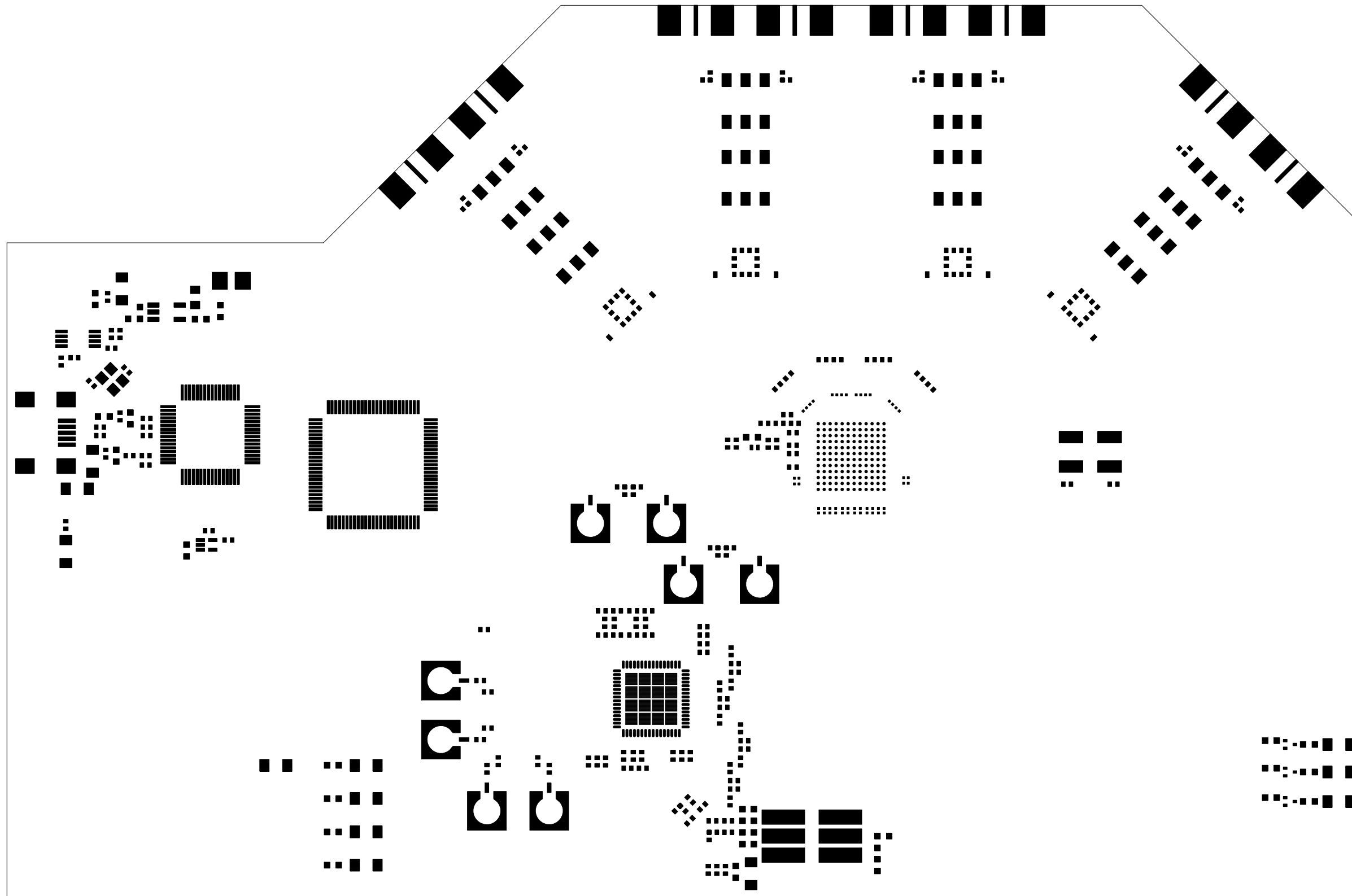
TEXAS INSTRUMENTS
DAC3XJ8X EVM REV D
SOLDERMASK TOP



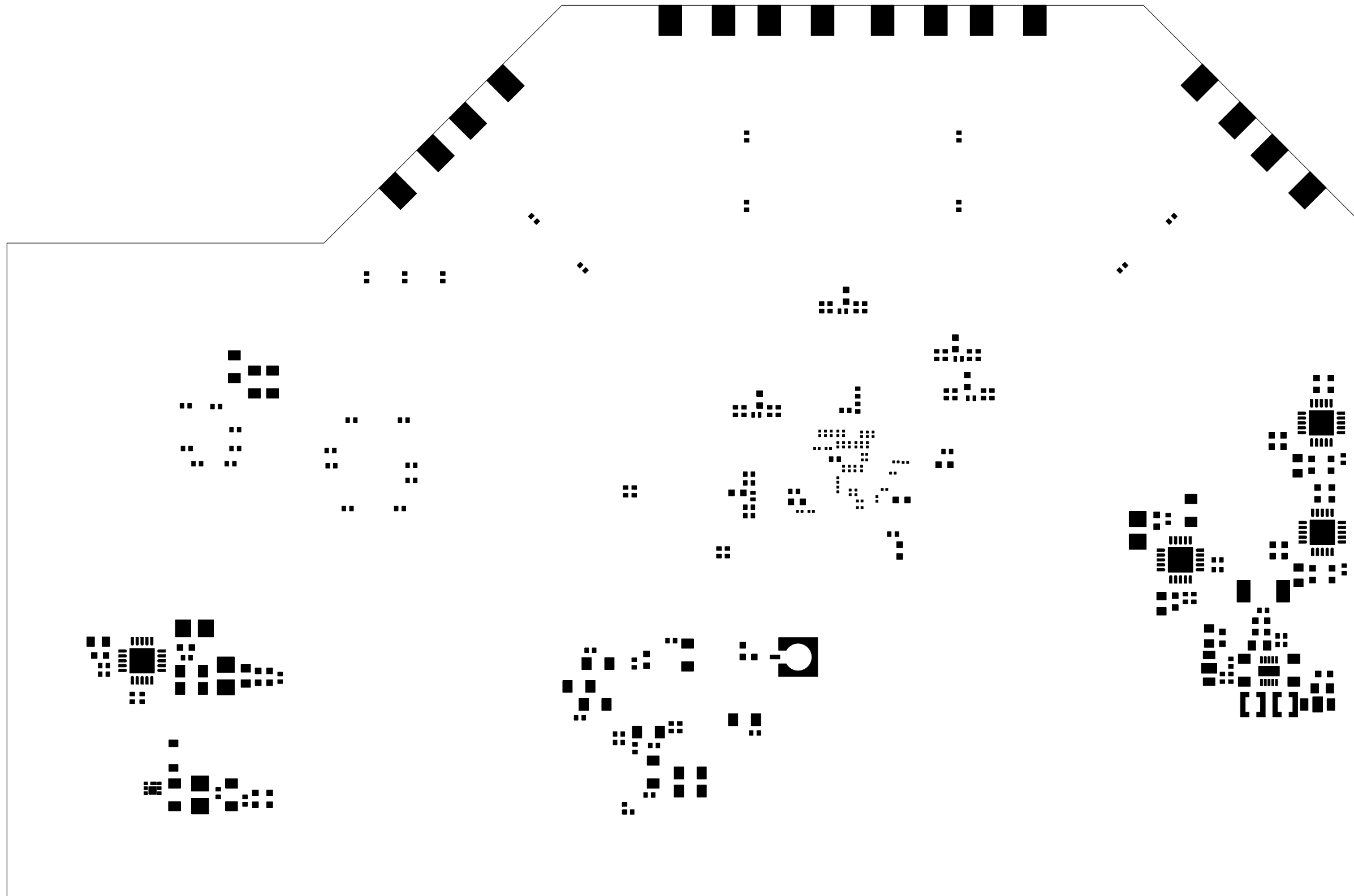


TEXAS INSTRUMENTS
DAC3XJ8X EVM REV D
SOLDERMASK BOTTOM

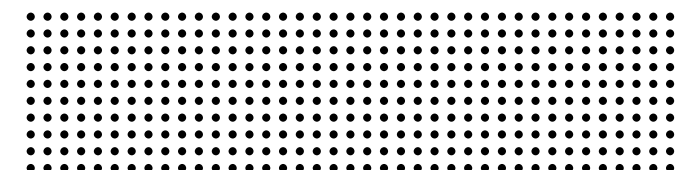


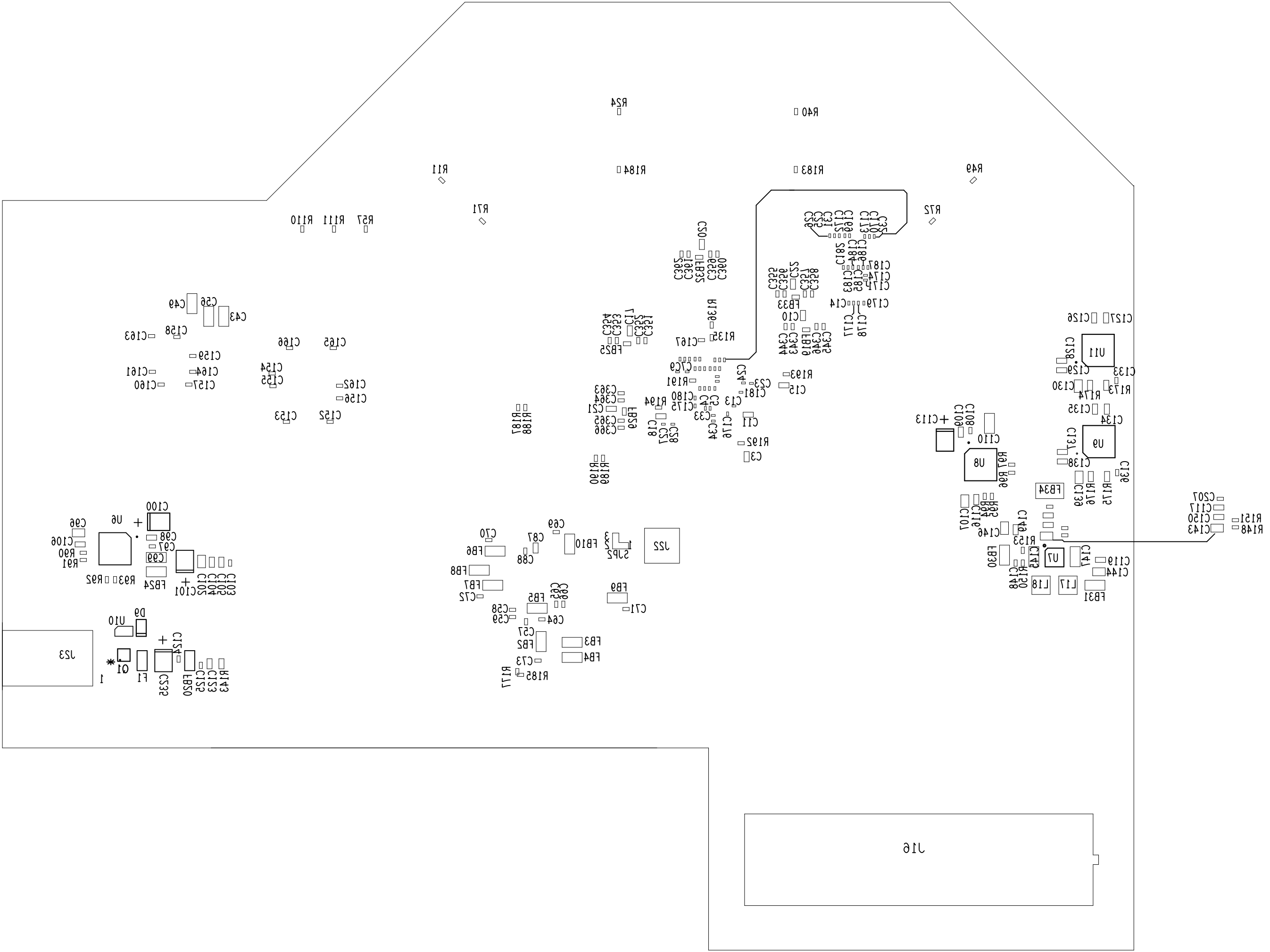


TEXAS INSTRUMENTS
DAC3XJ8X EVM REV D
PASTEMASK TOP



TEXAS INSTRUMENTS
DAC3XJ8X EVM REV D
PASTEMASK BOTTOM





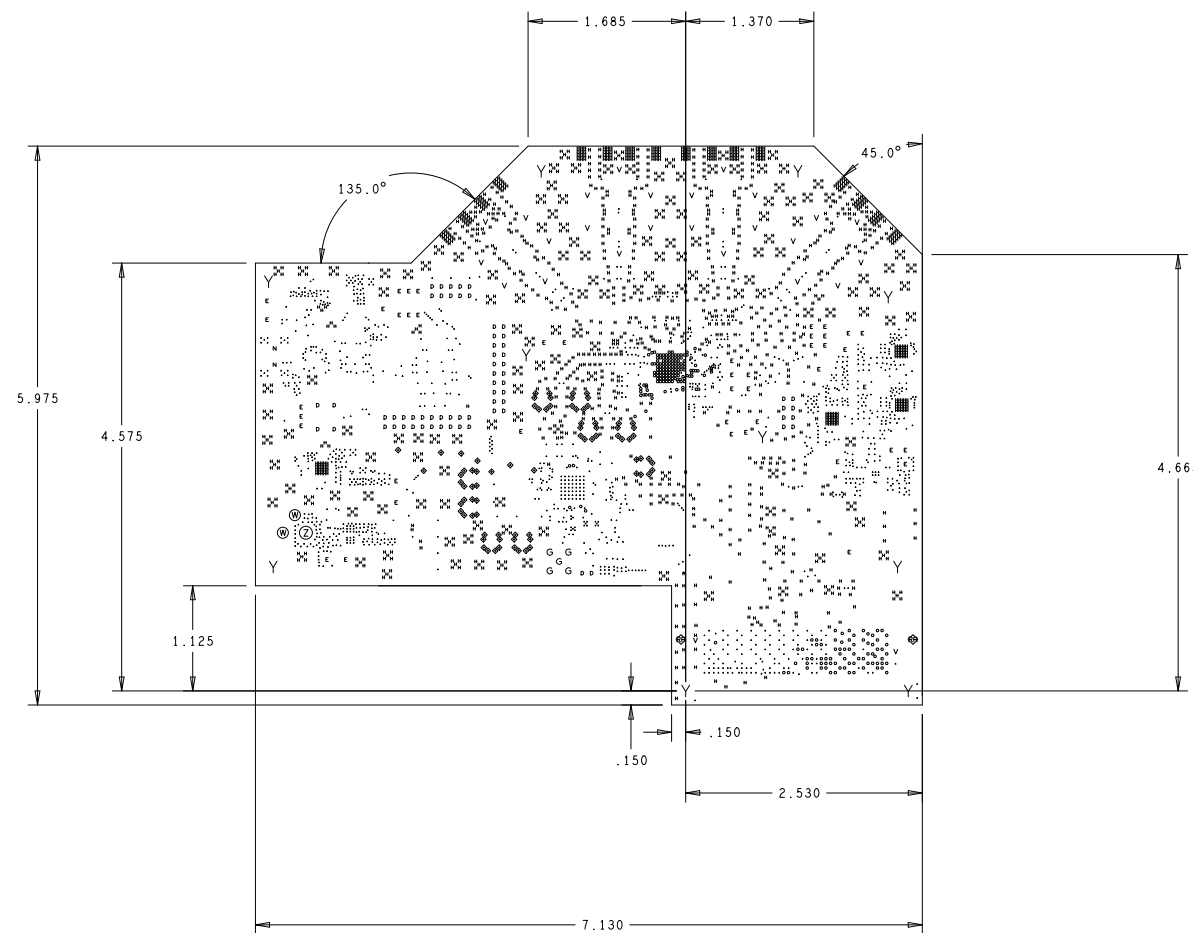
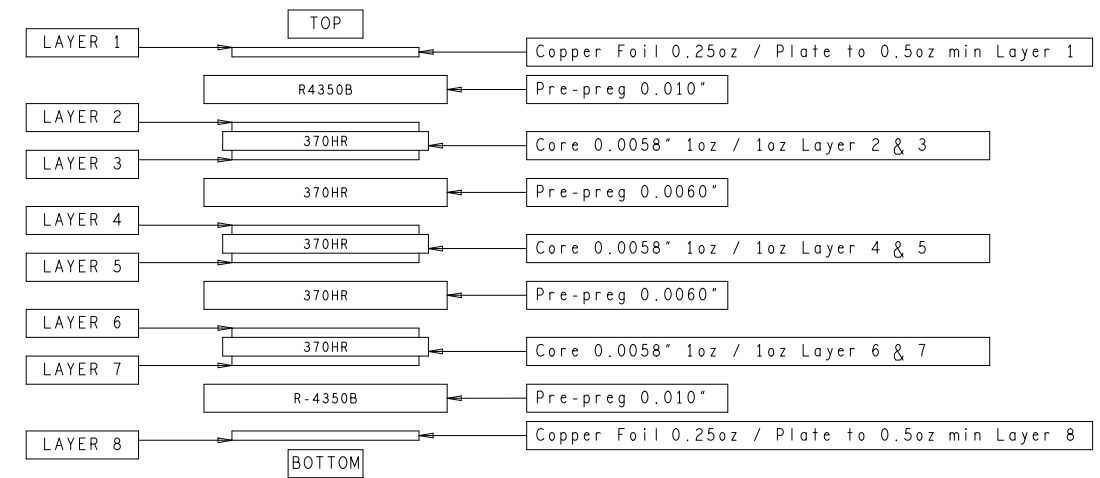
REVISIONS			
ZONE	LTR	DESCRIPTION	DATE

UNLESS OTHERWISE SPECIFIED, ALL NOTES ARE APPLICABLE.

- APPLICATION DESIGN, MANUFACTURING AND INSPECTION DOCUMENTS.
IPC-2221A & IPC-2222 / DESIGN STANDARD FOR RIGID PRINTED CIRCUIT BOARDS AND RIGID PRINTED BOARD ASSEMBLIES.
IPC-6012B / QUALIFICATION AND PERFORMANCE SPECIFICATION FOR RIGID PRINTED BOARD.
IPC-A-600G / ACCEPTABILITY OF PRINTED BOARDS.
- VIA 8, 10 & 12MIL SIZES APPLY AFTER PLATING. TOLERANCE TO BE $\pm .003/- .010$.
HOLE SIZE APPLY AFTER PLATING. TOLERANCE TO BE $\pm .003$.
- REGISTRATION TOLERANCE: ARTWORK $\pm .002$.
ALL HOLE CENTERS $\pm .005$ FROM DIMENSION DATUM.
- MINIMUM COPPER WALL THICKNESS SHALL BE .001 INCH.
FOR ALL PLATED THROUGH HOLES. BREAKOUT NOT ALLOWED.
- PROCESS AND MATERIAL MUST CONFORM TO UL 796. MATERIAL MUST MEET OR EXCEED UL FLAMMABILITY RATING 94V-0.
MATERIAL: MULTI-LAYER (SEE DETAIL 'A')
SEE LAYER STACKUP FOR ALL PRE-PREG & CORE THICKNESSES, COPPER OZ AND MATERIAL. FINISHED BOARD THICKNESS: .062 \pm 10%
- MANUFACTURE'S UL MARKING, FLAMMABILITY RATING, LOGO AND DATE CODE TO BE PLACED IN SILKSCREEN ON BOTTOM SIDE OF THE BOARD.
- SMOBC/IMMERSION GOLD: 2 - 8 μ IN OVER 118-236 μ IN NICKEL PLATING.
- SOLDERMASK BOTH SIDES USING TAIYO (OR EQUIVALENT)
COLOR = RED (0.001 TO 002" THICK OVER METAL.
- SILKSCREEN BOTH SIDES USING WHITE NPI LEADFREE.
REGISTRATION TOLERANCE TO BE $\pm .005$.
INK IS NOT ALLOWED ON EXPOSED PLATED AREA.
- P.C. BOARD TO BE FREE OF DIRT, OIL, FINGER PRINTS, ETC.
- BOARD WARPAGE: WARP AND TWIST SHALL NOT EXCEED .007 INCH PER INCH MEASURED AT ANY LOCATION OR DIRECTION ON THE BOARD.
- BOARD MUST BE 100% ELECTRICALLY TESTED TO ENSURE NO SHORTS OR OPEN CIRCUITS AT 20V.

- ALL OUTER LAYERS USING A 19MIL TRACE WIDTH SHALL BE 50 OHMS SINGLE ENDED \pm 10%.
- ALL OUTER LAYERS USING A 9MIL TRACE WIDTH AND 6MIL SPACING SHALL BE 100 OHMS DIFFERENTIAL \pm 10%.
- MINIMUM COPPER CONDUCTOR WIDTH IS: 4MIL.
MINIMUM COPPER CONDUCTOR SPACING IS: 5MIL.
- ALL INNER LAYER UNCONNECTED PADS SHALL BE REMOVED.
- PWB MUST BE ROHS COMPLIANT AND SURVIVE LEAD FREE ASSEMBLY.
MAX REFLOW OF 230 DEGREES C (6 PASSES).
- ALL THROUGH VIAS TO BE PLUGGED WITH NON-CONDUCTIVE EPOXY MATERIAL.
PLUGGED VIAS TO BE PLATED AFTER PLUGGING TO PRESENT FLAT SURFACE TO DEVICE.
NO POTHLES.

USE DDI/VIASYSTEMS STACKUP JOB NAME: DAC38J84 RO4350
THIS STACK UP DETAIL IS FOR REFERENCE ONLY



DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
*	8.0	PLATED	221
.	10.0	PLATED	1424
-	10.0	PLATED	3
•	12.0	PLATED	1754
+	15.0	PLATED	80
o	38.0	PLATED	64
e	40.0	PLATED	44
g	62.0	PLATED	1
o	67.0	PLATED	4
•	106.0	PLATED	2
o	120.0	PLATED	2
o	140.0	PLATED	1
n	39.0	NON-PLATED	2
v	50.0	NON-PLATED	2
v	53.0	NON-PLATED	24
Y	125.0	NON-PLATED	10

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES \pm .XX \pm .01 \pm . \pm .XXX \pm .005 \pm .	CONTRACT NO.		TEXAS INSTRUMENTS INC.	
	APPROVALS	DATE	FABRICATION DRAWING	
MATERIAL	DRAWN JV SMITH	12-18-12	DAC3XJ8X EVM	
SEE NOTE 5	ENG M GUIBORD	12-18-12	SIZE B	CODE IDENT NO. DRAWING NO. REV. D
FINISH	SEE NOTE 7, 8, 9		SCALE NONE	SHEET 1 OF 1
DO NOT SCALE DRAWING				

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